LNJ123W8GRAS

Surface Mounting Chip LED

Side View Bi-Color Type

■ Absolute Maximum Ratings T_a = 25°C

• Blue

Parameter	Symbol	Rating	Unit
Power dissipation	P_D	65	mW
Forward current	I_F	15	mA
Pulse forward current *1	I_{FP}	50	mA
Reverse direct current *2	I_{RDC}	100	mA
Operating ambient temperature	T_{opr}	–30 to +85	°C
Storage temperature	T_{stg}	–40 to +100	°C

Note) *1: The condition of I_{FP} is duty 10%, Pulse width 1 msec.
*2: I_{RDC} is a characteristic of the safeguard diode.

• Amber

Parameter	Symbol	Rating	Unit
Power dissipation	P_D	55	mW
Forward current	I_F	20	mA
Pulse forward current *	I_{FP}	60	mA
Reverse voltage	V_R	4	V
Operating ambient temperature	T_{opr}	–30 to +85	°C
Storage temperature	T_{stg}	–40 to +100	°C

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

■ Lighting Color / Lens Color

• Blue / White
• Amber / White

■ Electro-Optical Characteristics T_a = 25°C

• Blue

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity *	I_O		10	30		mcd
Forward current	I_F			5		mA
Forward voltage	V_F	I_F = 5 mA		3.1	3.7	V
Peak emission wavelength	λ_P	I_F = 5 mA		470		nm
Spectral half band width	$\Delta\lambda$	I_F = 5 mA		30		nm

Note) 1. Please give the setting to Blue: I_{FP} < 50 mA I_{FDC} < 12 mA when simulataneous light.
2. *: Measurement tolerance of luminous intensity: ±20%

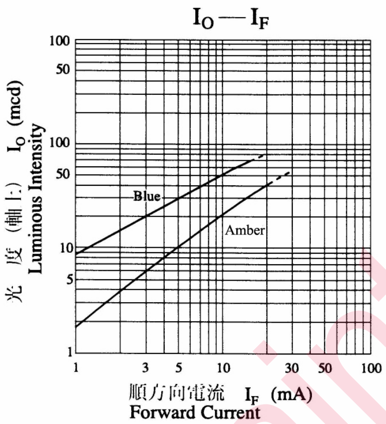
■ Electro-Optical Characteristics (Continued) $T_a = 25°C$

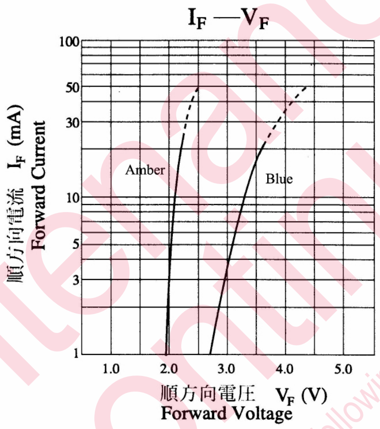
• Amber

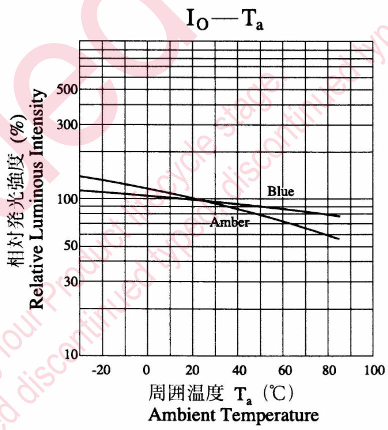
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity *	I_O		8.7	21		mcd
Forward current	I_F			10		mA
Forward voltage	V_F	$I_F = 10$ mA		2.1	2.6	V
Peak emission wavelength	λ_P	$I_F = 10$ mA		595		nm
Spectral half band width	$\Delta\lambda$	$I_F = 10$ mA		15		nm
Reverse current	I_R	$V_R = 4$ V			100	μA

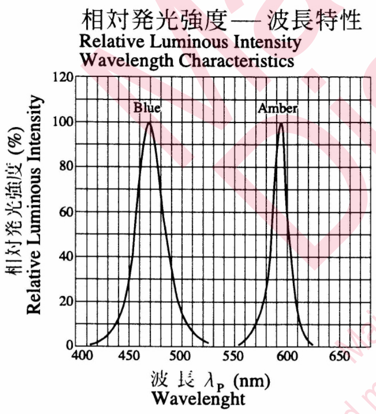
Note) 1. Please give the setting to Amber: $I_{FP} < 60$ mA $I_{FDC} < 18$ mA when simulataneous light.

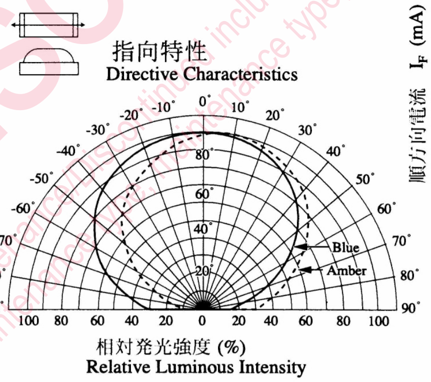
2. *: Measurement tolerance of luminous intensity: ±20%

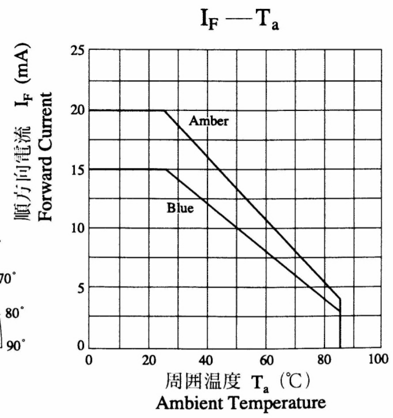




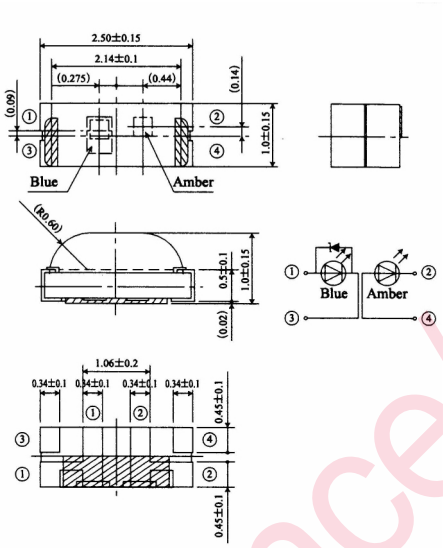








■ Package (Unit: mm)



• Pin name

1, 4: Anode

2, 3: Cathode

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